

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Customer Number: 89518  
Jin-Yuan Lee : Confirmation Number: 3369  
Application No.: 09/684,519 : Group Art Unit: 2841  
Patent No.: 6,809,935 : Issued: October 26, 2004  
For: THERMALLY COMPLIANT PCB SUBSTRATE FOR THE APPLICATION OF CHIP  
SCALE PACKAGES

TRANSMITTAL OF POWER OF ATTORNEY

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

## CERTIFICATE OF ELECTRONIC TRANSMISSION

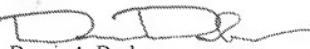
I hereby certify that this correspondence is being electronically transmitted to the  
United States Patent and Trademark Office on March 11, 2011.  
Patricia A. Balero  
Patricia A. Balero

Sir:

Transmitted herewith is a Fee Address Indication Form, Power Of Attorney to Prosecute  
Applications Before the USPTO, together with a Statement Under 37 CFR 3.73(b), which  
revokes all previous powers of attorney given in the above-identified application and associates  
the application with Customer Number 89518.

Respectfully submitted,

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Please recognize our Customer No. 89518  
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